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FLIP CHIP PACKAGING USING RECESSED INTERPOSER TERMINALS

ABSTRACT

A method and apparatus for packaging a semiconductor die with an interposer substrate. The semiconductor device assembly includes a conductively bumped semiconductor die and an interposer substrate having multiple recesses formed therein. The semiconductor die is mounted to the interposer substrate with the conductive bumps disposed in the multiple recesses so that the active surface of the semiconductor die is directly mounted to a facing surface of the interposer substrate. One or more openings may be provided in an opposing surface of the interposer substrate which extends to the multiple recesses and the bumps disposed therein and dielectric filler material introduced through the one or more openings into to the recesses.

[Figure 6B]